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November 2013

### FQPF33N10

# N-Channel QFET<sup>®</sup> MOSFET 100 V, 18 A, 52 m $\Omega$

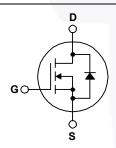
### **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

### **Features**

- 18 A, 100 V,  $R_{DS(on)}$  = 52 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 9 A
- Low Gate Charge (Typ. 38 nC)
- · Low Crss (Typ. 62 pF)
- · 100% Avalanche Tested
- · 175°C Maximum Junction Temperature Rating





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQPF33N10	Unit
V <sub>DSS</sub>	Drain-Source Voltage		100	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	18	Α
	- Continuous (T <sub>C</sub> = 100	)°C)	12.7	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	72	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	430	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	18	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		4.1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		6.0	V/ns
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		41	W
	- Derate above 25°C		0.27	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +175	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	FQPF33N10	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	3.70	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

### **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF33N10	FQPF33N10	TO-220F	Tube	N/A	N/A	50 units

### **Electrical Characteristics**

T<sub>C</sub> = 25°C unless otherwise noted.

	Parameter	Test Conditions	Min	Тур	Max	Uni
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		0.11		V/°(
I <sub>DSS</sub>	Zara Cata Valta na Duain Cumant	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, T <sub>C</sub> = 150°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9 A		0.040	0.052	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 9 A		20		S
<b>Dynami</b> C <sub>iss</sub>	ic Characteristics Input Capacitance			1150	1500	pF
	<u> </u>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$		320	420	pF
C <sub>oss</sub>	Output Capacitance Reverse Transfer Capacitance			62	80	pr pF
C <sub>rss</sub>	Reverse Transier Capacitance			02	00	рг
Switchi	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 33 A,		15	40	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		195	400	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	(Note 4)		80	170	ns
t <sub>f</sub>	Turn-Off Fall Time			110	230	ns
	Total Gate Charge	V <sub>DS</sub> = 80 V, I <sub>D</sub> = 33 A,		38	51	nC
Qg	Total Outo Ollargo					
Q <sub>g</sub> Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V	/	7.5		nC

I <sub>S</sub>	Maximum Continuous Drain-Source Dio	de Forward Current	 	18	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	orward Current	 	72	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 18 A	 	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, I}_{S} = 33 \text{ A,}$	 80		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$	 0.22	/	μC

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2. L = 2 mH,  $I_{AS}$  = 18 A,  $V_{DD}$  = 25 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C. 3.  $I_{SD}$   $\leq$  33 A,  $di/dt \leq$  300 A/µs,  $V_{DD}$   $\leq$  B  $V_{DSS}$ , starting  $T_{J}$  = 25°C. 4. Essentially independent of operating temperature.

### **Typical Characteristics**

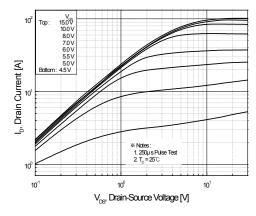


Figure 1. On-Region Characteristics

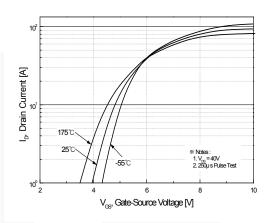


Figure 2. Transfer Characteristics

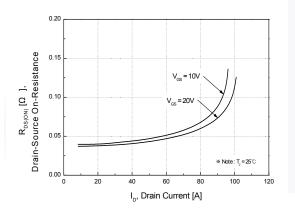


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

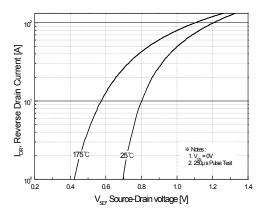


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

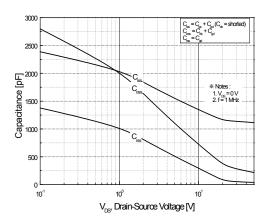


Figure 5. Capacitance Characteristics

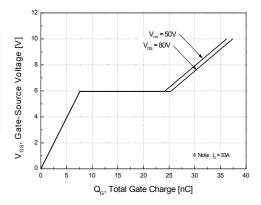
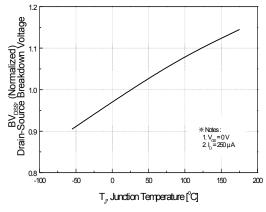


Figure 6. Gate Charge Characteristics

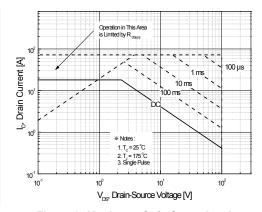
### Typical Characteristics (continued)



30 25 (Dezignation Temperature [°C]

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



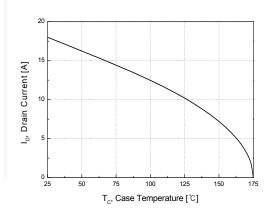


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

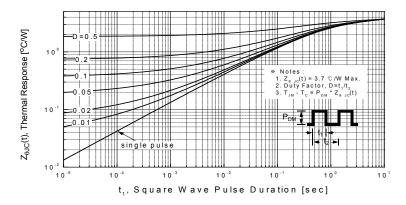


Figure 11. Transient Thermal Response Curve



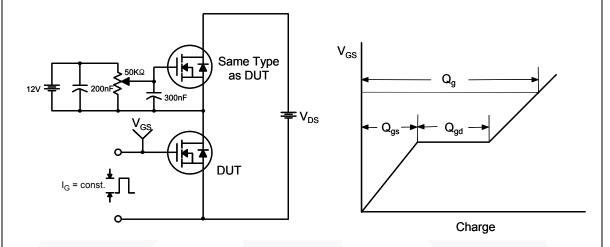


Figure 13. Resistive Switching Test Circuit & Waveforms

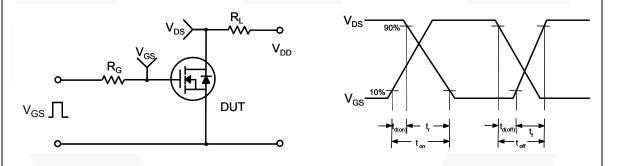
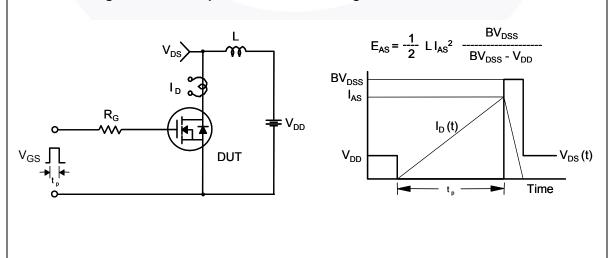
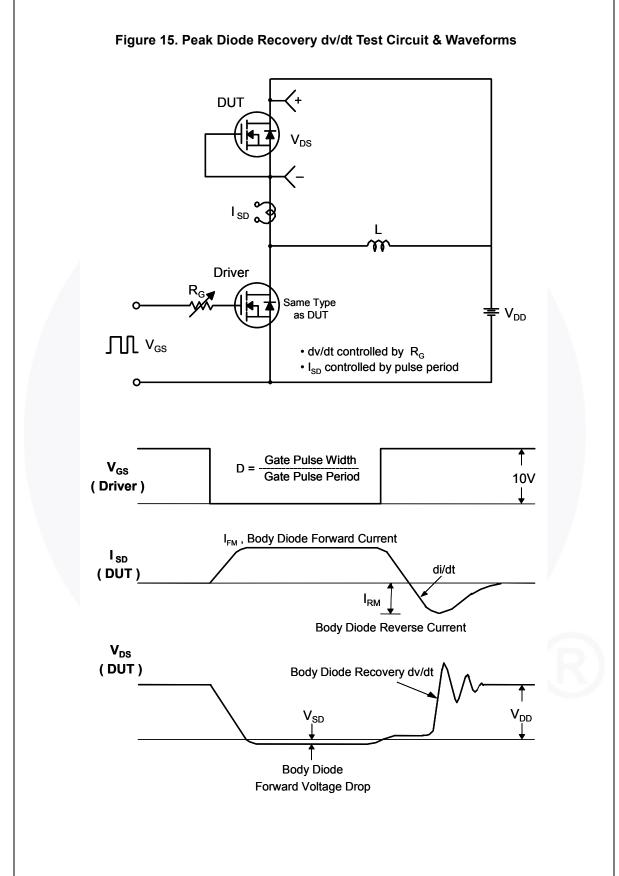


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





### **Mechanical Dimensions**

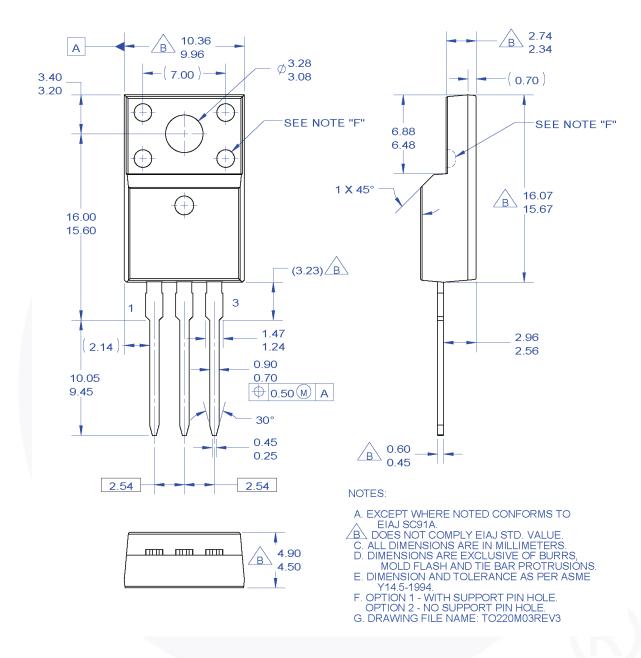


Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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